PAD 1 REFERENCE

WLCSP10 3.2x2.1x0.14

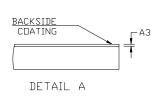
CASE 567XT ISSUE O

В

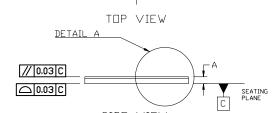
DATE 02 APR 2019

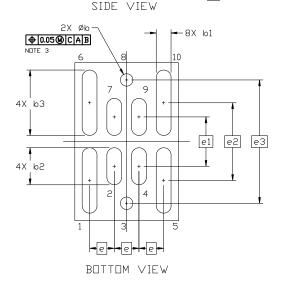
NUTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. POSITIONAL TOLERANCE APPLIES TO ALL PADS.



	MILLIMETERS			
DIM	MIN.	N□M.	MAX.	
Α	0.11	0.14	0.17	
A3	0.04 REF			
b	0.22	0.25	0.28	
b1	0.27	0.30	0.33	
b2	0.72	0.75	0.78	
b 3	1.295	1.325	1.355	
D	3.17	3,20	3.23	
Е	2.07	2.10	2.13	
е	0.50 BSC			
e1	1.0 BSC			
e2	1.575 BSC			
e3	2.50 BSC			





GENERIC

MARKING DIAGRAM*

XX

AYWZZ.

XX

Α

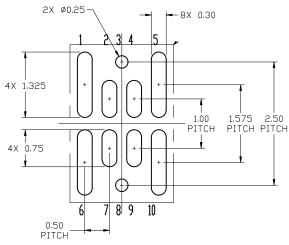
Υ

W

ZZ

= Year

= Work Week



RECOMMENDED MOUNTING FOOTPRINT*

For additional information on our Pb-Free strategy and soldering details, please download the DN Seniconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	WLCSP10 3.2x2.1x0.14		PAGE 1 OF 1

Specific Device CodeAssembly Location

= Assembly Lot Code

= Pb-Free Package

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